



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Gap Filler 1000 (Two-Part)

Thermally Conductive, Liquid Gap Filling Material

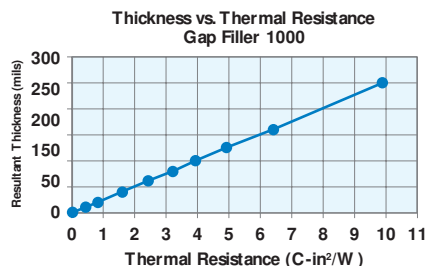
Features and Benefits

- Thermal conductivity: 1.0 W/m-K
- Ultra-conforming, designed for fragile and low-stress applications
- Ambient and accelerated cure schedules
- 100% solids – no cure by-products
- Excellent low and high temperature mechanical and chemical stability



Gap Filler 1000 is a thermally conductive, liquid gap filling material. It is supplied as a two-component, room or elevated temperature curing system. The material is formulated to provide a balance of cured material properties highlighted by a low modulus and good compression set (memory). The result is a soft, thermally conductive, form-in-place elastomer ideal for coupling "hot" electronic components mounted on PC boards with an adjacent metal case or heat sink. Before cure, Gap Filler 1000 flows under pressure like a grease. After cure, it does not pump from the interface as a result of thermal cycling. Unlike thermal grease, the cured product is dry to the touch. Unlike cured gap filling materials, the liquid approach offers infinite thickness with little or no stress during displacement and eliminates the need for specific pad thickness and die-cut shapes for individual applications. Gap Filler 1000 is intended for use in thermal interface applications when a strong structural bond is not required.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP FILLER 1000			
PRO PERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color / Part A	Gray	Gray	Visual
Color / Part B	White	White	Visual
Viscosity as Mixed (cps) (1)	100,000	100,000	ASTM D 2196
Density (g/cc)	1.6	1.6	ASTM D 792
Mix Ratio	1:1	1:1	—
Shelf Life @ 25°C (months)	6	6	—
PRO PERTY AS CURED			
Color	Gray	Gray	Visual
Hardness (Shore 00) (2)	30	30	ASTM D 2240
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Continuous Use Temp (°F) / (°C)	-76 to 347	-60 to 175	—
ELECTRICAL AS CURED			
Dielectric Strength (V/mil)	500	500	ASTM D 149
Dielectric Constant (1000 Hz)	5.0	5.0	ASTM D 150
Volume Resistivity (Ohm-meter)	10 ¹¹	10 ¹¹	ASTM D 257
Flame Rating	V-O	V-O	U.L. 94
THERMAL AS CURED			
Thermal Conductivity (W/m-K)	1.0	1.0	ASTM D 5470
CURE SCHEDULE			
Pot Life @ 25°C (min) (3)	15	15	—
Cure @ 25°C (min) (4)	60 - 120	60 - 120	—
Cure @ 100°C (min) (4)	5	5	—

1) Brookfield RV, Heli-Path, Spindle TF @ 20 rpm, 25°C.
2) Thirty second delay value Shore 00 hardness scale.
3) Time for viscosity to double.
4) Cure schedule (rheometer - time to read 90% cure)

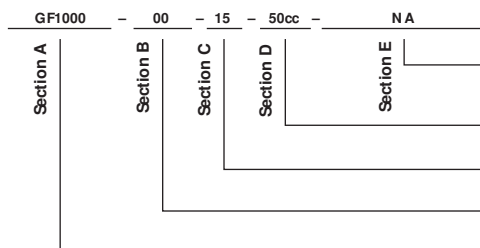
Typical Applications Include:

- Automotive electronics
- Computer and peripherals
- Between any heat-generating semiconductor and a heat sink
- Telecommunications
- Thermally conductive vibration dampening

Configurations Available:

- Supplied in cartridge and kit form

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.

Standard Options

example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Cartridges: 50cc = 50.0cc, 400cc = 400.0cc
Kits: 1200cc = 1200.0cc, or 10G = 10 gallon

Pot Life: 15 = 15 minutes

00 = No spacer beads
07 = 0.007" spacer beads

GF1000 = Gap Filler 1000 Material

Gap Pad®: U.S. Patent 5,679,457 and others



www.bergquistcompany.com

The Bergquist Company -
North American Headquarters
18930 West 78th Street
Chanhassen, MN 55317
Phone: 800-347-4572
Fax: 952-835-0430

The Bergquist Company -
European Headquarters
Bramenberg 9a, 3755 BT Eemnes
Netherlands
Phone: 31-35-5380684
Fax: 31-35-5380295

The Bergquist Company - Asia
Room 15, 8/F Wah Wai Industrial Centre
No. 38-40, Au Pui Wan Street
Fotan, Shatin, N.T. Hong Kong
Phone: 852-2690-9295
Fax: 852-2690-2344

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